



## **Multi Field Cross Scale Collaborative Design Methods and Technologies for Chip Manufacturing and Integration**

*Prof. Sheng LIU, Academician of CAS, Wuhan University,  
China*

### **Speaker's Biography:**

Sheng Liu is a professor at Wuhan University, a Ph.D. at Stanford University, an ASME Fellow and an IEEE Fellow. He is an expert in the field of micro-nano manufacturing and a leader in domestic chip packaging technology. He was elected as an academician of the Chinese Academy of Sciences in 2023. Academician Liu Sheng has achieved systematic innovation results in micro-nano manufacturing science and engineering technology (involving integrated circuits, light-emitting diodes LED, micro-sensors, power electronics IGBT and other chip packaging). As the first completer, he won the first prize of the 2020 National Science and Technology Progress Award, the second prize of the 2016 National Technology Invention Award, the first prize of the 2015 Ministry of Education Technology Invention Award, the 2018 First Prize of the Electronic Society Technology Invention Award, and the 2009 IEEE International Electronics Award. Outstanding Technical Achievement Award of the Packaging Society (1 person per year in the world, the first person in China), 2009 Special Achievement Award of the China Electronics Society, 1997 International Microelectronics and Packaging Society (IMAPS) Technical Contribution Award, 1995 U.S. Presidential Professor Award (30 in that year) people), and was selected into the first batch of National Distinguished Youth (overseas) projects in 1999 (only 7 people were selected that year). Published 424 SCI papers, more than 6,600 SCI citations, 6 monographs (4 in English), and 196 authorized invention patents.